

CLAIMS

We claim:

- 1 1. A polish pad comprising:
2 a base layer; and
3 an ion exchange layer disposed on the base layer.
- 1 2. The polish pad of claim 1, wherein the ion exchange layer comprises ion
2 exchange resin beads
- 1 3. The polish pad of claim 1, wherein the ion exchange layer comprises ground ion
2 exchange resin beads.
- 1 4. The polish pad of claim 2, wherein the ion exchange beads are pressed into the
2 ion exchange layer.
- 1 5. The polish pad of claim 3, wherein the ground ion exchange beads are pressed
2 into the ion exchange layer.
- 1 6. The polish pad of claim 1, further comprising a base support layer.
- 1 7. The polish pad of claim 1, wherein the ion exchange layer is patterned.
- 1 8. The polish pad of claim 6, wherein the base support layer is patterned.

1 9. The polish pad of claim 8, wherein the base support layer and the ion exchange
2 layer is patterned.

1 10. The polish pad of claim 1, wherein the ion exchange layer binds cations.

1 11. The polish pad of claim 10, wherein the ion exchange layer binds copper
2 cations.

1 12. An ion exchange polish pad comprising:
2 a base layer; and
3 a resin layer having ion exchange material embedded therein.

1 13. The ion exchange polish pad of claim 12, wherein the ion exchange material is
2 ion exchange resin beads.

1 14. The ion exchange polish pad of claim 12, wherein the ion exchange material is
2 ion exchange resin powder.

1 15. The ion exchange polish pad of claim 12, wherein the resin layer is patterned.

1 16. The ion exchange polish pad of claim 12, wherein the base layer is patterned.

1 17. The ion exchange polish pad of claim 12, wherein the polishing layer and the
2 support layer is patterned.

22. The method of fabricating an ion exchange polish pad as in claim 21, further comprising patterning the first resin mixture layer.

32. The method of claim 31, wherein the polymer component is a pre-polymer.